

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: H. C. Cranford, Jr. et al;

Application No.: 09/996,091

Filed: Nov. 28, 2001

Group No.: 2189

Examiner: Rupal Dharia

For: Architecture for Advanced Serial Link Between Two Cards

Commissioner for Patents  
Washington, D.C. 20231

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STATEMENT FOR INFORMATION DISCLOSURE  
UNDER 37 C.F.R. § 1.97(e)

IDENTIFICATION OF INFORMATION DISCLOSURE STATEMENT  
FOR WHICH THIS STATEMENT IS BEING MADE

1. This statement is being made for the Information Disclosure Statement accompanying this statement.

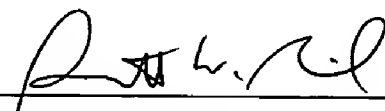
STATEMENT

2. I, the person signing below, state that each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement. 37 C.F.R. § 1.97(e)(1).

IDENTIFICATION OF PERSON MAKING THIS STATEMENT

3. The person making this certification is:
  - (a) the practitioner who signs below on the basis of the information in the practitioner's file.

Date: March 4, 2003

  
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